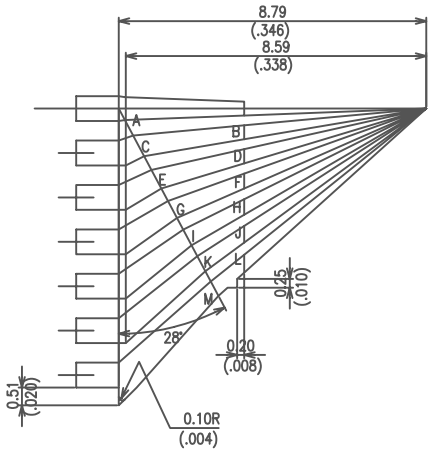
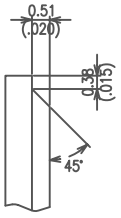
SSM P/N: CQJ05203

NOTES
1.MATERIALS
CERAMIC TO OPAQUE,90–94% AL_2O_3
SOLDER GLASS TO BE 7583.
MAX PULLBACK TO BE 0.25(.010)
FROM CERAMIC EDGE.
DIE ATTACH AREA TO BE Au 120
MICROINCH MIN.
LEAD FRAME TO BE ALLOY 42 OR
EQUIVALENT WITH ALUMINIUM
BOND PADS, 100 MICROINCH THICK
AND 35 MILS IN LENGTH WITH NO
PULL BACK.
3.THERE WILL BE NO UNSUPPORTED
BOND PADS GRATER THAN 0.25(.010)
4.ADJACENT BOND PADS MUST BE
CO–PLANAR WITHIN 0.15(.006)
TOTAL CO–PLANARITY NO GRATER
THAN 0.25(.010).
5.THERE WILL BE NO NICKS,CUTS
OR GLASS IN THE BOND RADIUS
6.MINIMUM INTERNAL METAL
SEPARATION OTHER THAN BOND FINGERS
TO BE 0.15(.006)

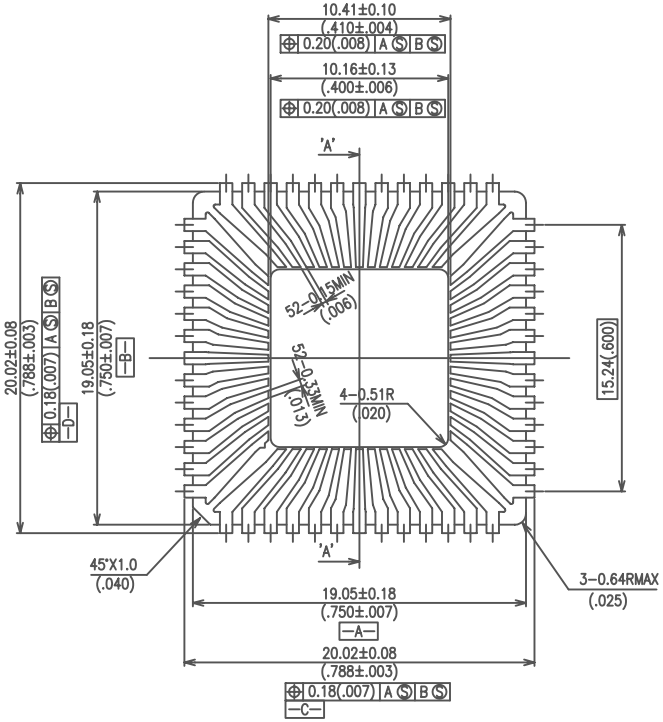
No.	ANGLE
A	2.18 °
B	5.25 °
C	9.58 °
D	12.59 °
E	16.78 °
F	19.68 °
G	23.70 °
H	26.47 °
I	30.24 °
J	32.83 °
K	36.36 °
L	38.76 °
M	42.02 °

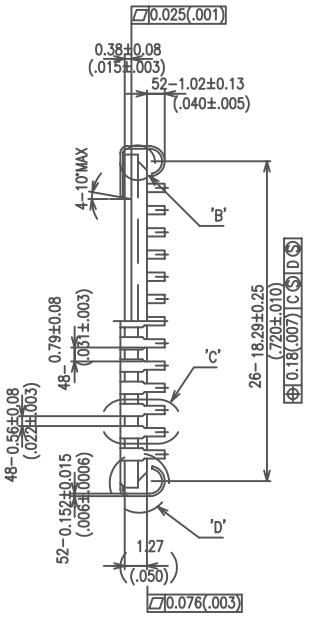


LEADTIP DETAIL

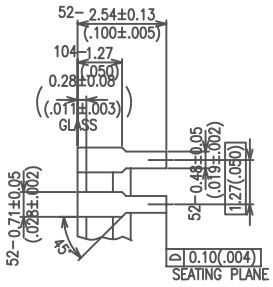


VIEW B

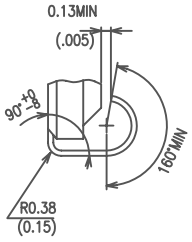




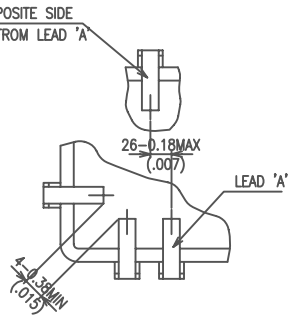
SECTION A–A



VIEW C



VIEW D



JEDEC TYPE

MODIFICATIONS					
	CHANGE	DATE	DRAWN	CHECKED	APPROVED

NAME: 52LD QUAD CERPAC'J'(750–400)
SCALE: 5 : 1
MATERIAL:
TOLERANCES: UNLESS OTHERWISE SPECIFIED
DRAWN | CHECKED
APPROVED | DATE: FEB.06'89
KYOCERA CORPORATION KYOTO JAPAN
DWG No. QC–052215–J–1